	7

L Number	Hits	Search Text	DB	Time stamp
1	50	(copper near clad) same (laser near5 (carbon near dioxide))	USPAT;	2003/01/13 10:31
	ļ		US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
	_		IBM_TDB	0000/04/40 40:44
2	2.	((copper near clad) same (laser near5 (carbon near dioxide)))	USPAT;	2003/01/13 10:14
		and ((wav\$2 or corrugat\$3) same (copper near foil))	US-PGPUB;	
			EPO; JPO;	
	į		DERWENT;	
_	404	//	IBM_TDB	2002/04/42 00:36
3	494	((wav\$2 or corrugat\$3) same (copper near foil))	USPAT; US-PGPUB;	2003/01/13 09:36
			EPO; JPO;	
i			DERWENT;	
			IBM_TDB	1
	15	(((wav\$2 or corrugat\$3) same (copper near foil))) same	USPAT;	2003/01/13 09:36
4	15	((wav\$2 or configat\$3) same (copper flear foil))) same	US-PGPUB;	2003/01/13 03:30
		(copper near ciad)	EPO; JPO;	
			DERWENT;	
			IBM TDB	•
5	205	(copper near3 particle) same (copper near foil)	USPAT;	2003/01/13 10:13
-	203	(copper ricare particle) sainte (copper ricar lon)	US-PGPUB;	2000
			EPO; JPO;]
			DERWENT;	
			IBM_TDB	
6	107	((copper near3 particle) same (copper near foil)) and (printed	USPAT;	2003/01/13 11:54
	10,	near circuit near board or "PCB" or printed near wiring near	US-PGPUB;	F 10. 14. 10
		board or "PWB")	EPO; JPO;	
		board of 1 115)	DERWENT;	
1			IBM_TDB	
7	5	(((copper near3 particle) same (copper near foil)) and (printed	USPAT;	2003/01/13 10:01
·		near circuit near board or "PCB" or printed near wiring near	US-PGPUB;	1 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1
		board or "PWB")) and ((copper near clad) same (laser near5	EPO; JPO;	
ļ		(carbon near dioxide)))	DERWENT;	
	<i>'''</i>	IBM_TDB		
8 2500	(copper near2 laminate) same (copper near foil)	USPAT;	2003/01/13 10:14	
			US-PGPUB;	MA 15.74
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	l
9	24	((copper near2 laminate) same (copper near foil)) and ((wav\$2	USPAT;	2003/01/13 10:35
		or corrugat\$3) same (copper near foil))	US-PGPUB;	
			EPO; JPO;	•
			DERWENT;	
	_		IBM_TDB	0000/04/40 40:00
10	2	(((copper near2 laminate) same (copper near foil)) and	USPAT;	2003/01/13 10:30
	,	((wav\$2 or corrugat\$3) same (copper near foil))) and ((copper	US-PGPUB;	
		near clad) same (laser near5 (carbon near dioxide)))	EPO; JPO; DERWENT;	
			IBM TDB	
44	^	(((conner near) laminate) same (conner near failt) and	USPAT;	2003/01/13 10:31
11	3	(((copper near2 laminate) same (copper near foil)) and ((wav\$2 or corrugat\$3) same (copper near foil))) and (laser	US-PGPUB;	2000/01/10 10.51
İ			EPO; JPO;	
-		near5 (carbon near dioxide))	DERWENT;	
		IBM_TDB		
12	17	(bulk near copper) same (copper near foil)	USPAT;	2003/01/13 10:35
14	17	(built fleat copper) same (copper fleat foil)	US-PGPUB;	
			EPO; JPO;	· · · ·
			DERWENT;	
			IBM_TDB	
13	8	((bulk near copper) same (copper near foil)) and rough\$3	USPAT;	2003/01/13 10:36
13	0	((Julia Hour copper) carrie (copper Hour forly) and roughte	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	•
			IBM_TDB	
14	1764	plat\$3 same (copper near clad)	USPAT;	2003/01/13 11:52
• •		· · · · · · · · · · · · · · · · · · ·	US-PGPUB	1

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15	608	(plat\$3 same (copper near clad)) and (resist same etch\$3)	USPAT; US-PGPUB	2003/01/13 11:53
16	517	((plat\$3 same (copper near clad)) and (resist same etch\$3)) and (printed near circuit near board or "PCB" or printed near wiring near board or "PWB")	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/01/13 12:29
17	517	(((plat\$3 same (copper near clad)) and (resist same etch\$3)) and (printed near circuit near board or "PCB" or printed near wiring near board or "PWB")) and @pd<200000516	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/01/13 12:00
18	517	((plat\$3 same (copper near clad)) and (resist same etch\$3)) and (printed near circuit near board or "PCB" or printed near wiring near board or "PWB")	USPAT; US-PGPUB	2003/01/13 12:00
19	398	(((plat\$3 same (copper near clad)) and (resist same etch\$3)) and (printed near circuit near board or "PCB" or printed near wiring near board or "PWB")) and @pd<20000516	USPAT; US-PGPUB	2003/01/13 12:01
20	336	(via or hole or open\$3) same (laser near (carbon near dioxide))	USPAT; US-PGPUB	2003/01/13 12:03
21	3	((((plat\$3 same (copper near clad)) and (resist same etch\$3)) and (printed near circuit near board or "PCB" or printed near wiring near board or "PWB")) and @pd<20000516) and ((via or hole or open\$3) same (laser near (carbon near dioxide)))	USPAT; US-PGPUB	2003/01/13 12:04
22	2106	(printed near wiring near board or "PWB") and (plat\$3 same via)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/01/13 12:43
23	3	((printed near wiring near board or "PWB") and (plat\$3 same via)) and (bulk near copper)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/01/13 12:41
24	361	((printed near wiring near board or "PWB") and (plat\$3 same via)) and (etch\$3 same resist)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/13 12:44
25	172	(((printed near wiring near board or "PWB") and (plat\$3 same via)) and (etch\$3 same resist)) and @pd<20000516	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/13 12:45
26	3	((((printed near wiring near board or "PWB") and (plat\$3 same via)) and (etch\$3 same resist)) and @pd<20000516) and ((copper near clad) same laser)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/13 12:46